

Peter Schneider

List of Publications by Year in descending order

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Version: 2024-02-01

26
papers

146
citations

2258059

3
h-index

1872680

6
g-index

28
all docs

28
docs citations

28
times ranked

83
citing authors

#	ARTICLE	IF	CITATIONS
1	Fraunhofer's Initial and Ongoing Contributions in 3D IC Integration. , 2019, , .		0
2	Simulation platform for application development on a vision-system-on-chip with integrated signal processing. Journal of Electronic Imaging, 2016, 25, 041004.	0.9	1
3	Current and future 3D activities at Fraunhofer. , 2015, , .		1
4	Design rule check and layout versus schematic for 3D integration and advanced packaging. , 2014, , .		1
5	Electro-thermal co-design of chip-package-board systems. , 2013, , .		1
6	System level simulation " A core method for efficient design of MEMS and mechatronic systems. , 2012, , .		6
7	Sensitivity analysis and adaptive multi-point multi-moment model order reduction in MEMS design. Analog Integrated Circuits and Signal Processing, 2012, 71, 49-58.	1.4	2
8	FunctionalDMU: Co-Simulation of Mechatronic Systems in a Virtual Environment. , 2011, , .		4
9	Design of multi-dimensional magnetic position sensor systems based on HallinOne^{Â®} technology. , 2010, , .		12
10	Integration of multi physics modeling of 3D stacks into modern 3D data structures. , 2010, , .		2
11	Developing digital test sequences for through-silicon vias within 3D structures. , 2010, , .		18
12	Simulation of electro-thermal interaction. , 2010, , .		2
13	Challenges of simulating robust wireless sensor network applications in building automation environments. , 2010, , .		8
14	Modular modeling approach to consider RF and thermal behavior of complex systems built up using interconnect structures in 3D integration. , 2010, , .		1
15	Towards a methodology for analysis of interconnect structures for 3D-integration of micro systems. Analog Integrated Circuits and Signal Processing, 2008, 57, 205-211.	1.4	7
16	Model based sensor system for temperature measurement in R744 air conditioning systems. , 2008, , .		0
17	Design support for Wireless Sensor Networks based on the IEEE 802.15.4 standard. , 2008, , .		8
18	Design Support for 3D System Integration by Multi Physics Simulation. , 2008, , .		3

#	ARTICLE	IF	CITATIONS
19	System Level Modeling of the Relevant Physical Effects of Inertial Sensors Using Order Reduction Methods. Analog Integrated Circuits and Signal Processing, 2005, 44, 129-135.	1.4	1
20	System Level Modeling of Microsystems Using Order Reduction Methods. Analog Integrated Circuits and Signal Processing, 2003, 37, 7-16.	1.4	11
21	<title>MOSCITO: a program system for MEMS optimization</title>. , 2002, , .		3
22	<title>System-level simulation of acoustic devices</title>. , 2002, 4755, 343.		0
23	<title>System-level modeling of microsystems using order reduction methods</title>. , 2002, , .		7
24	A modular approach for simulation-based optimization of MEMS. Microelectronics Journal, 2002, 33, 29-38.	2.0	22
25	<title>Model library and tool support for MEMS simulation</title>. , 2001, , .		11
26	Modular approach for simulation-based optimization of MEMS. , 2000, 4228, 71.		12